

**In the Specification:**

Replace the first paragraph on page 1, lines 2- 6 with the following paragraph.

A' This application is a continuation-in-part of ~~US~~ U.S. Patent Application Serial No. 09/387,084, filed 08/31/1999, titled "Methods and Apparatus for Controlling and/or Measuring Additive Concentration in an Electroplating Bath" (now issued as U.S. Patent No. 6,356,033), which is a continuation of PCT/US99/09659, filed 05/03/1999 and published in English under PCT Article 21(2), titled "Methods and Apparatus for Controlling and/or Measuring Additive Concentration in an Electroplating Bath", which claims priority from U.S. Provisional Patent Application Serial No. 60/083,882, filed May 1, 1998, entitled "Closed Loop Electrolyte Composition Monitoring and Control System for Copper Interconnect Applications". ~~both of which~~ The disclosures of these applications are incorporated herein by reference in their entireties.